

SEMI International Standards



Organizational Chart

- Europe
- Japan
- Korea
- North America
- Taiwan

Last updated: December 16, 2009

SEMI Europe Regional Standards Organization

Co-chairs: Jean-Marie Collard – Solvay Chemicals, Werner Bergholz - Jacobs University of Bremen

Compound Semiconductor Materials Committee

C: R. Bindermann - FCM
C: A. Weber - SiCrystal

Gases & Liquid Chemicals Committee

C: J-M Collard – Solvay Chemicals
C: G. Ferrier - Air Products
VC: G. De Vos - FFEM

EHS Committee

C: B. Planting – ASML
C: open

Equipment Automation Committee

C: A. Honold - InReCon (I&C, PIC, Metrics)
C: M. Carrubba - Numonyx (I&C, PIC)
C: L. Pfitzner - FhG IISB (Metrics)
VC: F. Petzold - Trustsec (I&C)

Facilities Committee

C: D. Rutterswoerden - M+W Zander
C: J. Schuchart - Siemens

MEMS Committee

C: G. Fernholz – VDI/VDE/IT
C: U. Behringer - UBC

Photovoltaic Committee

C: L. Fabry - Wacker Chemie
C: H. Aulich - PV Crystalox Solar

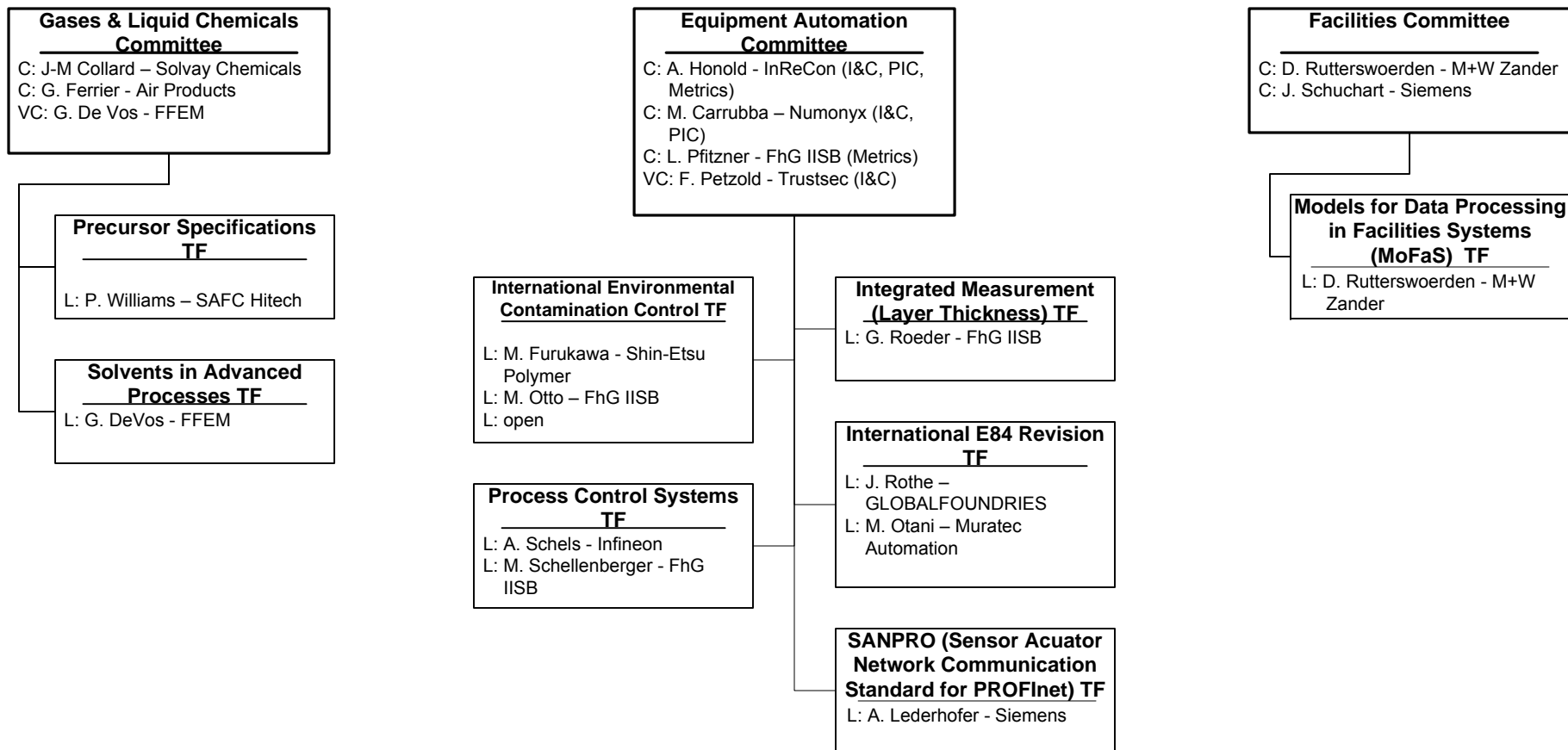
Micropatterning Committee

C: U. Behringer - UBC
C: J. Waelpoel – ASML

Silicon Wafer Committee

C: W. Bergholz - Jacobs University of Bremen
C: P. Wagner - Consultant

SEMI Europe Regional Standards Organization (cont'd)



SEMI Europe Regional Standards Organization (cont'd)

Micropatterning Committee
C: U. Behringer - UBC
C: J. Waelpoel - ASML

**Compound Semiconductor
Materials Committee**
C: R. Bindemann - FCM
C: A. Weber - SiCrystal

EHS Committee
C: B. Planting - ASML
C: open

MEMS Committee
C: U. Behringer - UBC

**Contactless Resistivity
and Mobility Mapping TF**
L: W. Jantz - Semimap

SiC TF
L: A. Weber - SiCrystal

**Global GaSb Wafer
Specification TF**
L: I. Grant - Wafer Technology

Carbon in GaAs TF
L: H.C. Alt - FHM

EPD in GaAs TF TF
L: U. Kretzer - FCM

**SEMI S10 Revision (Risk
Assessment) TF**
L: A. Brown - Rushbrook
L: B. Planting - ASML

MESS-C TF
L: B. Planting - ASML

SEMI Europe Regional Standards Organization (cont'd)

Photovoltaic Committee
C: L. Fabry - Wacker Chemie
C: H. Aulich - PV Crystalox Solar

**PV Equipment Interface
Specification (EIS) TF**

L: T. Vonderstrass –
SolarWorld
L: M. Glaser – Manz
Automation

**Int'l PV Analytical Test
Methods TF**

L: Richard Hockett – Evans
Analytical Group
L: Bhushan Sopori – NREL

**PV Materials (Connector
Ribbon) TF**

L: Christian Prischmann –
Ulbrich

PV Silicon Materials TF

L: Peter Wagner – Consultant

PV Transport Carrier TF

L: Joachim Seidelmann –
Fraunhofer IPA
L: Tino Kömer -- Q-Cells SE

Silicon Wafer Committee

C: W. Bergholz - Jacobs University of
Bremen
C: P. Wagner - Consultant

**International Terminology
TF**

L: P. Wagner - Consultant
L: M. Bullis - Materials &
Metrology
L: T. Naritomi - SUMCO

**International Advanced Wafer
Geometry (AWG) TF**

L: P. Langer - Consultant
L: S. Akiyama - Raytex
L: F. Passek - Siltronic

**International Advanced
Surface Inspection TF**

L: J. Stover - The Scatter
Works
L: G. Kren - KLA-Tencor
L: H. Ohta - Hitachi

**International Test
Methods TF**

L: P. Wagner - Consultant

SEMI Japan Regional Standards Organization

Co-Chair: Shigeru Kobayashi – Renesas Technology Co-Chair: Makoto Yamamoto – Muratec Automation
Vice Chair: Supika Mashiro – Canon ANELVA

Information & Control Committee

C: Mitsune Sakamoto - TEL
C: Takayuki Nishimura -
Dainippon Screen Mfg.

Silicon Wafer Committee

C: Naoyuki Kawai - Renesas
C: Toshio Naritomi - SUMCO

Environmental Health & Safety Committee

C: Hidetoshi Sakura - Intel
C: Supika Mashiro - Canon
ANELVA
C: Moray Crawford – Hatsuta
Seisakusho

FPD Factory Automation Committee

C: Yasunobu Otagawa - Daihen
C: Harumichi Hirose - Shibaura
Mechatronics

Special Groups

Reporting to the JRSC

Physical Interfaces & Carriers Committee

C: Akira Kashimoto – Shin-Etsu
Polymer
C: Shoji Komatsu - Acteon
C: Kenjiro Nawa - TEL

Photovoltaic Committee

C: Hiromu Takatsuka –
Mitsubishi Heavy Industry
C: Kazuhiko Kashima –
Covalent Materials
C: Terry Asakawa - TEL

Gases & Facilities Committee

C: Hiromichi Enami - Hitachi
High-Technologies
C: Isao Suzuki - MKS Japan

FPD Color Filter & Optical Elements Committee

C: Hisashi Aruga - Seiko Epson
C: Tadahiro Furukawa - Kyodo
Printing
C: Hiromitsu Itoh - Toppan Printing

Standardization Process Integration TF

L: Supika Mahiro - Canon
ANELVA

Metrics Committee

C: Hisao Kuroda - MES AFTY
C: Mikio Furukawa - Shin-Etsu
Polymer

Compound Semiconductor Materials Committee

C: Masayoshi Obara (SEH)
C: TBD

Liquid Chemicals Committee

C: Hiroshi Tomita - Toshiba

FPD Mask Committee

C: Atsushi Okazaki - SK-Electronics

FPD Coordination Group

L: Yoshitada Nogami - SK
Electronics
L: Makoto Yamamoto - Muratec

Traceability Committee

C: Michio Honma - NEC
Electronics
C: Yasuji Nakamura -
Yaskawa Electric

Packaging Committee

C: Kazunori Kato - AiT
C: Haruo Tabata – Osaka
University
C: Yutaka Koma - Advisor

Micropatterning Committee

C: Iwao Higashikawa - Toshiba

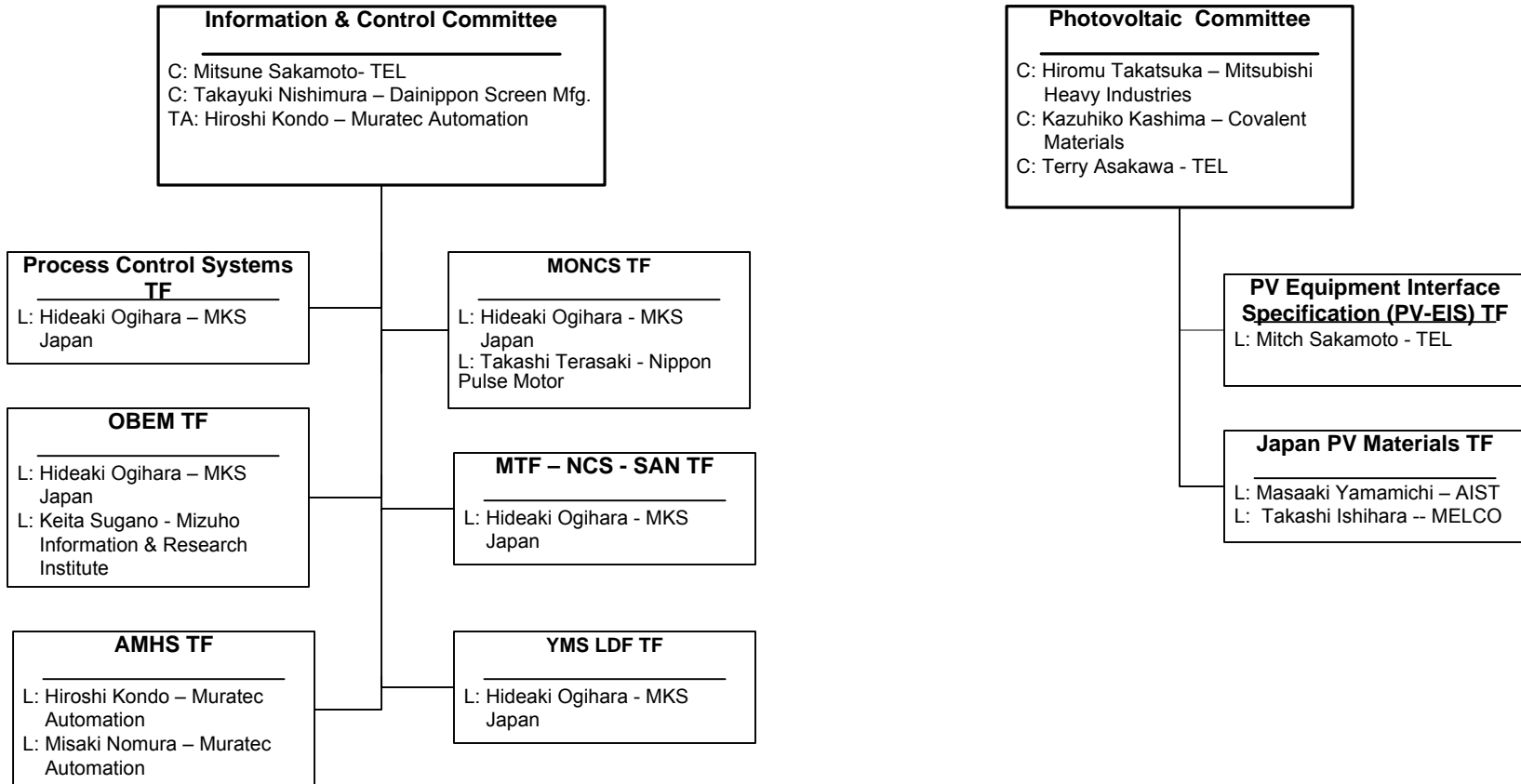
FPD Metrology Committee

C: Shinsuke Katoh – Sharp
C: Ryoichi Watanabe – Toshiba
Movie Display
C: Yuji Yoda – Otsuka Electronics

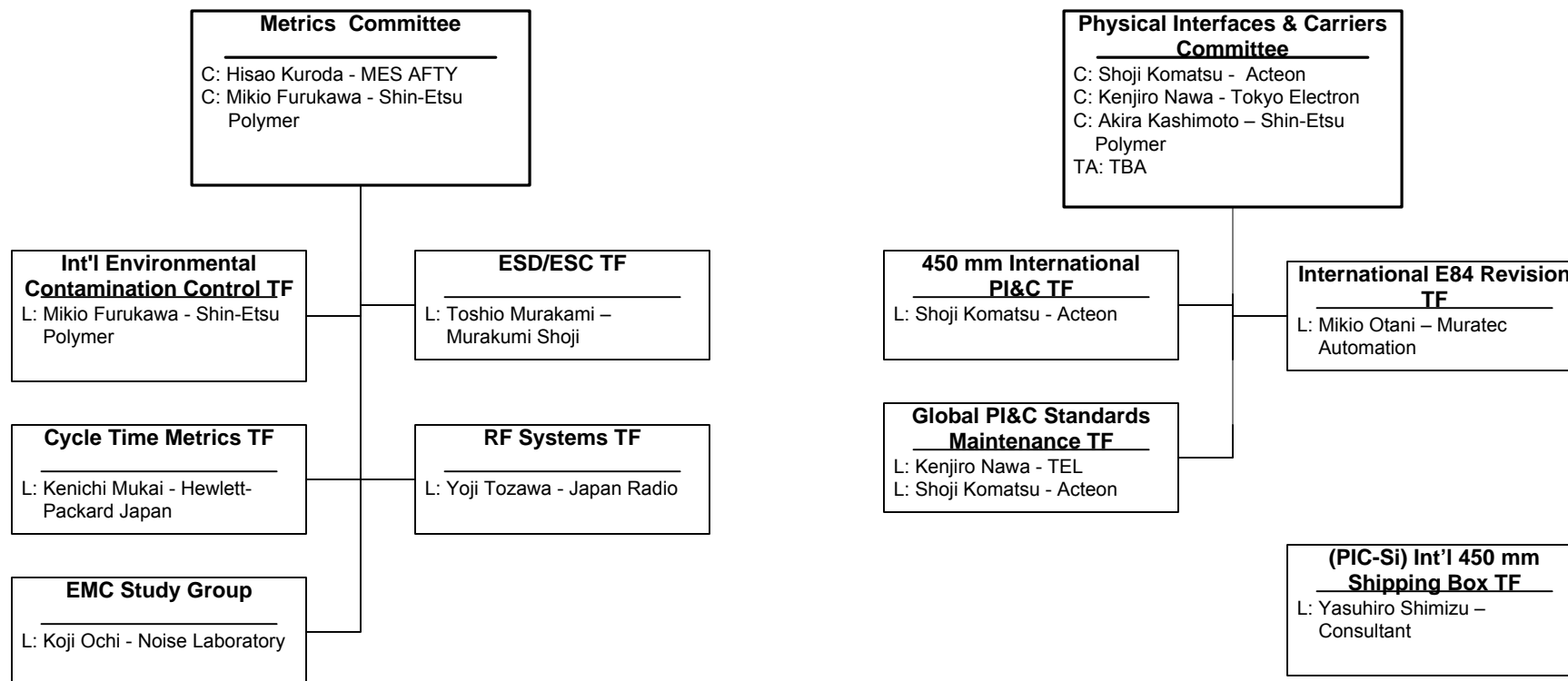
Test Committee

C: Hiroshi Kaga - NECEL
C: Hidetoshi Aibara -
Yokogawa Electric

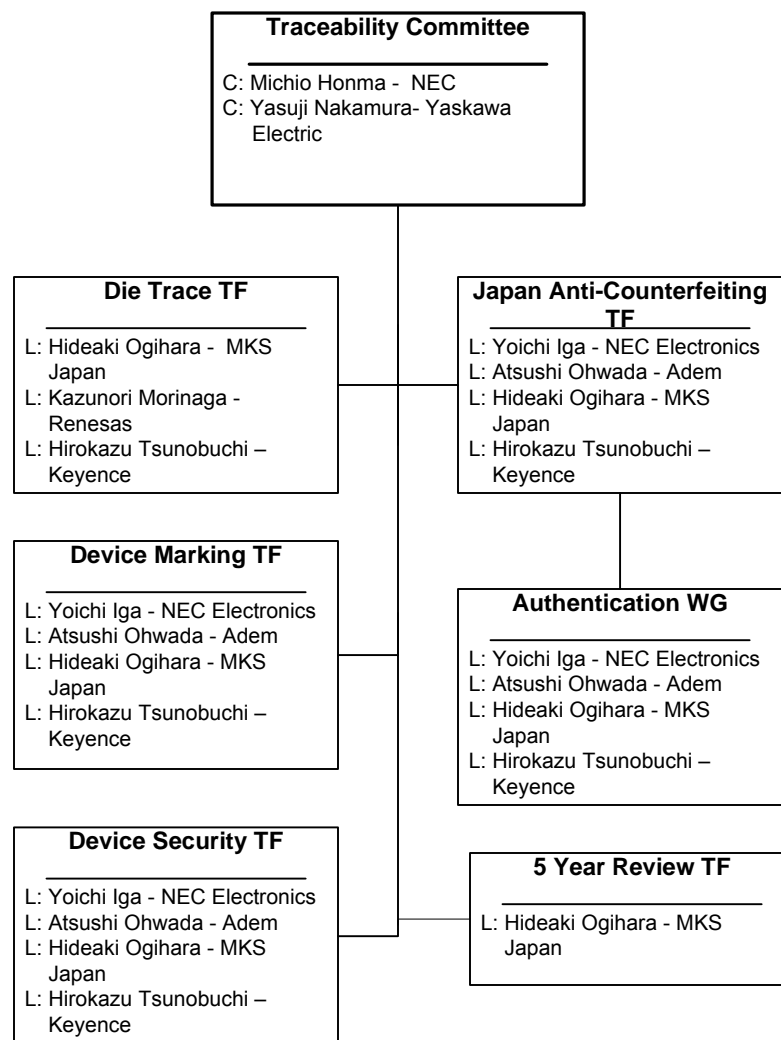
SEMI Japan Information & Control and PV Committees



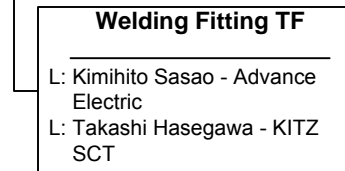
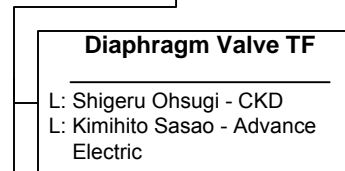
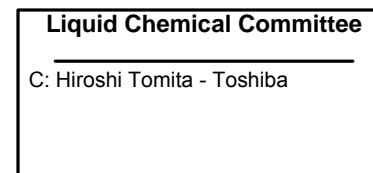
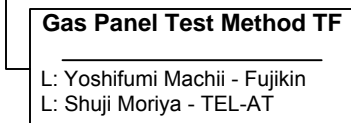
SEMI Japan PI&C and Metrics Committees



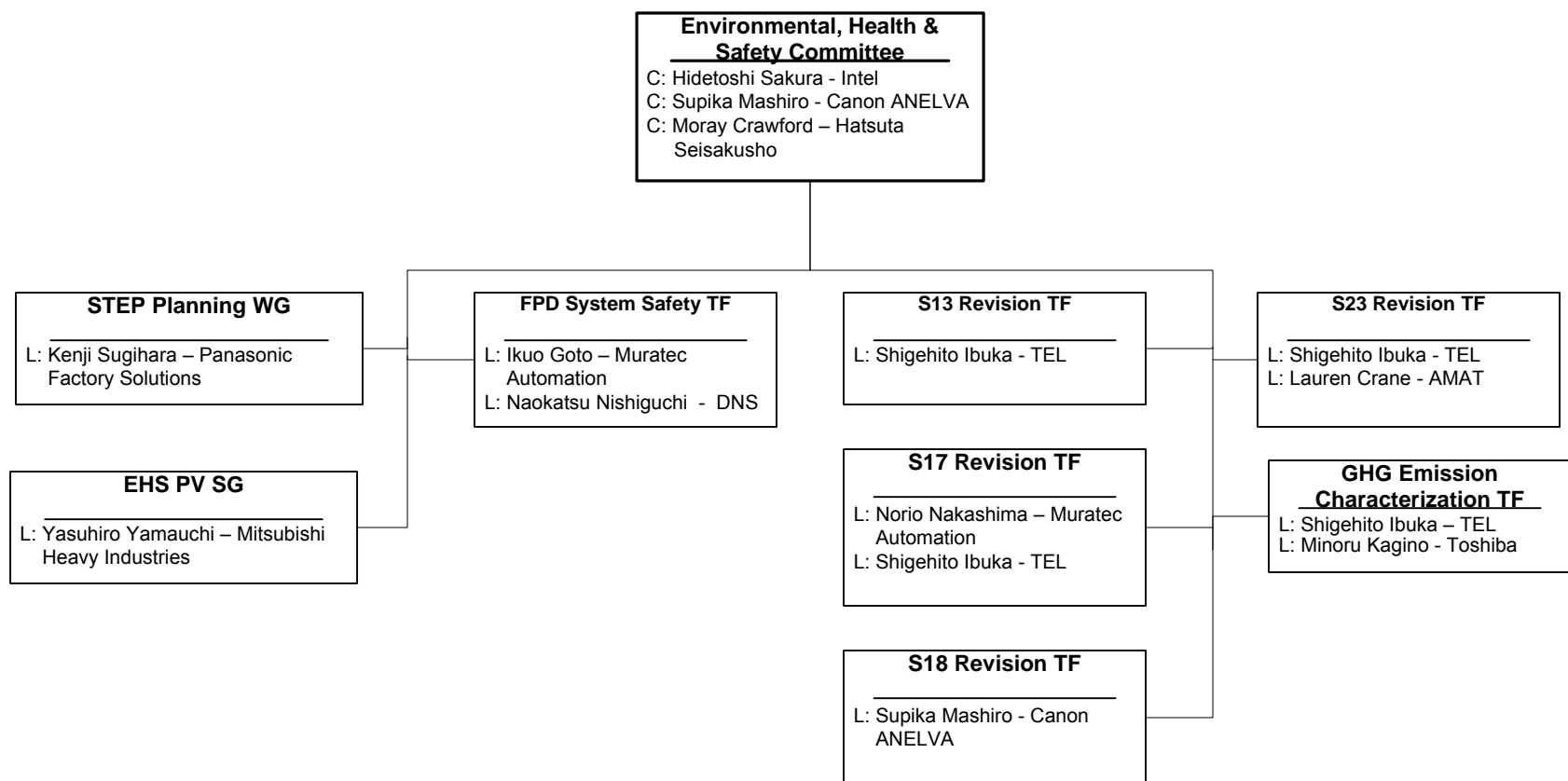
SEMI Japan Traceability Committee



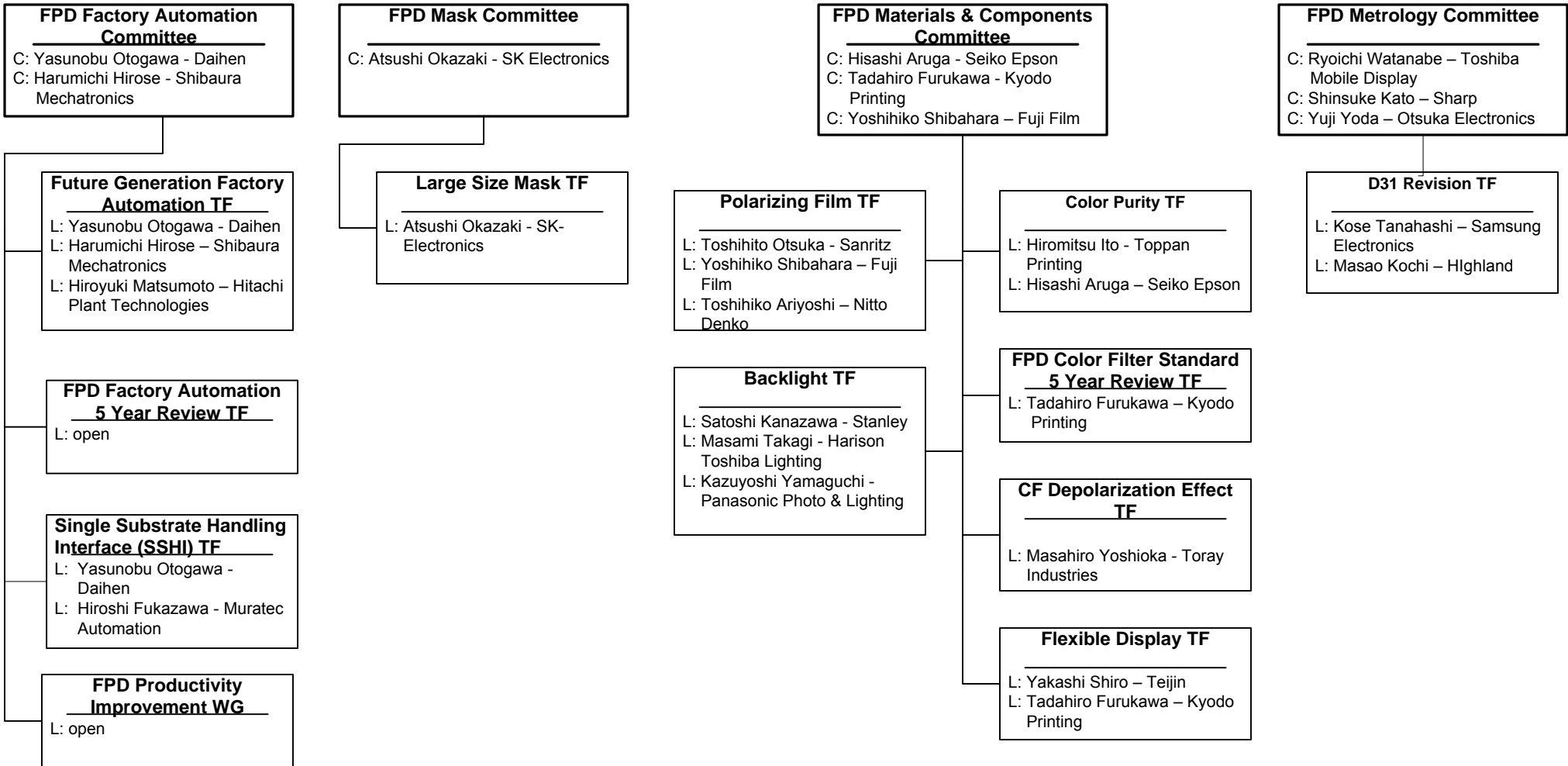
SEMI Japan Gases & Facilities, LC Committees



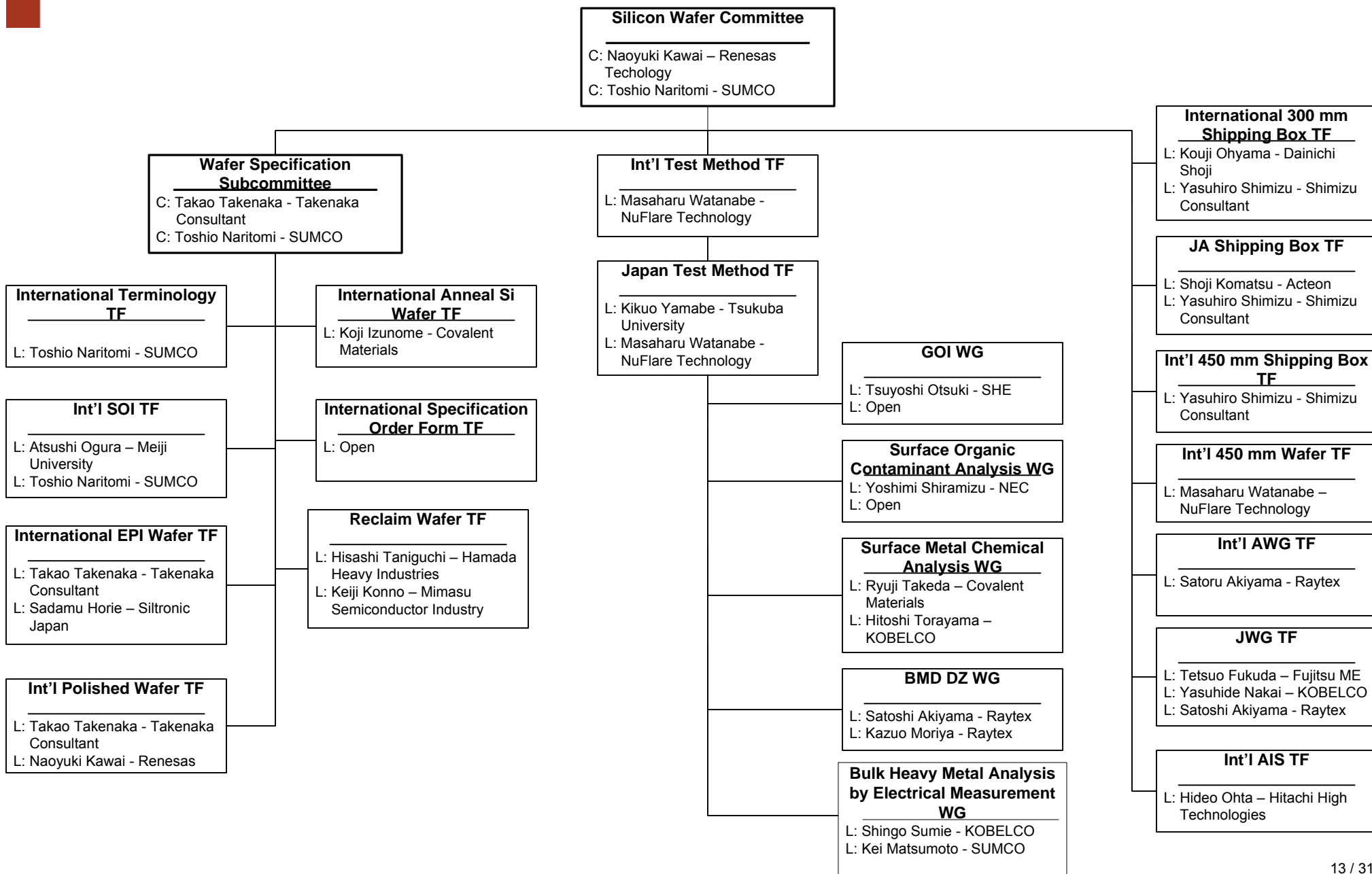
SEMI Japan EHS Committee



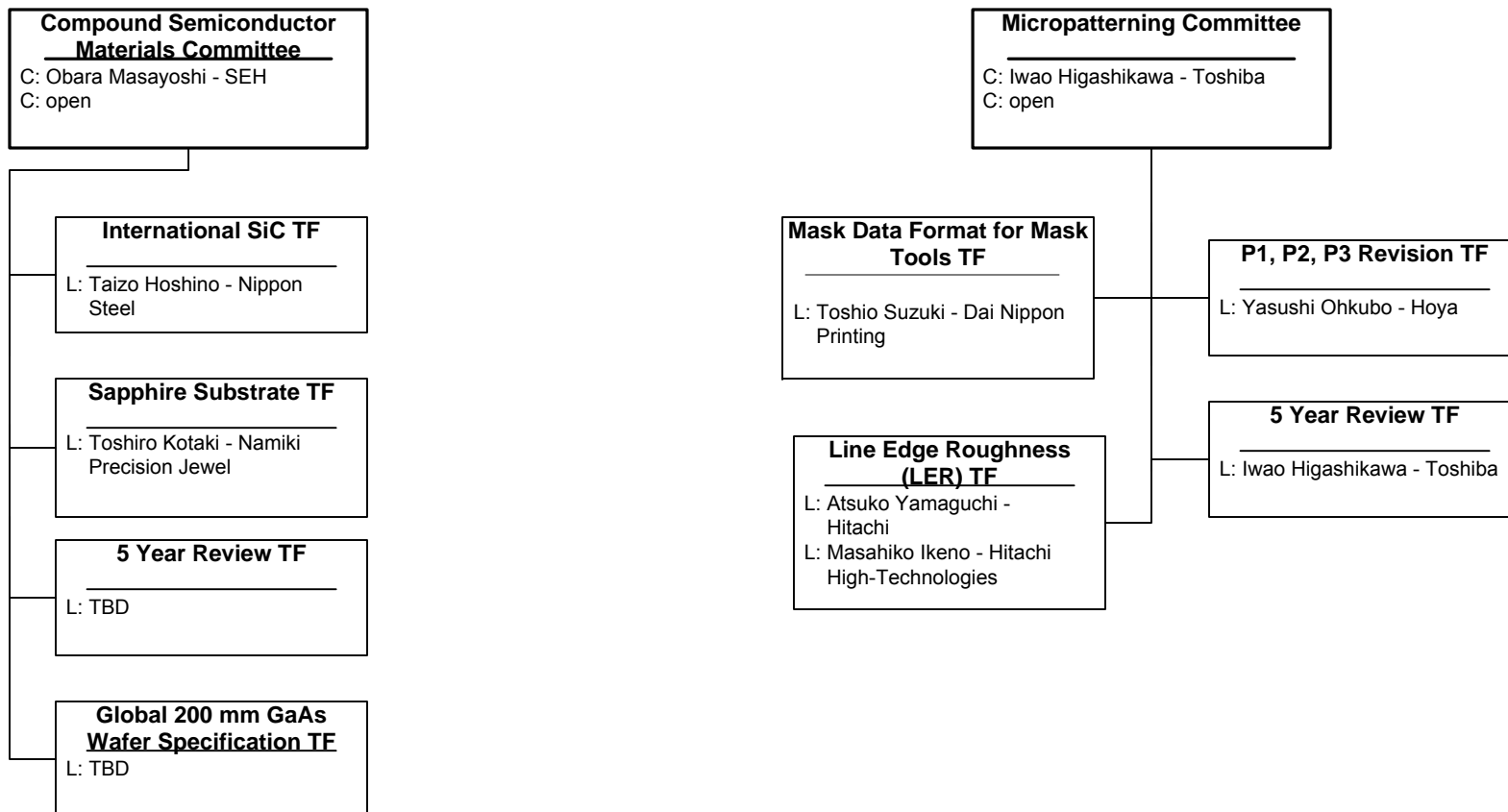
SEMI Japan FPD FA, CFOE, Mask, & Metrology Committees



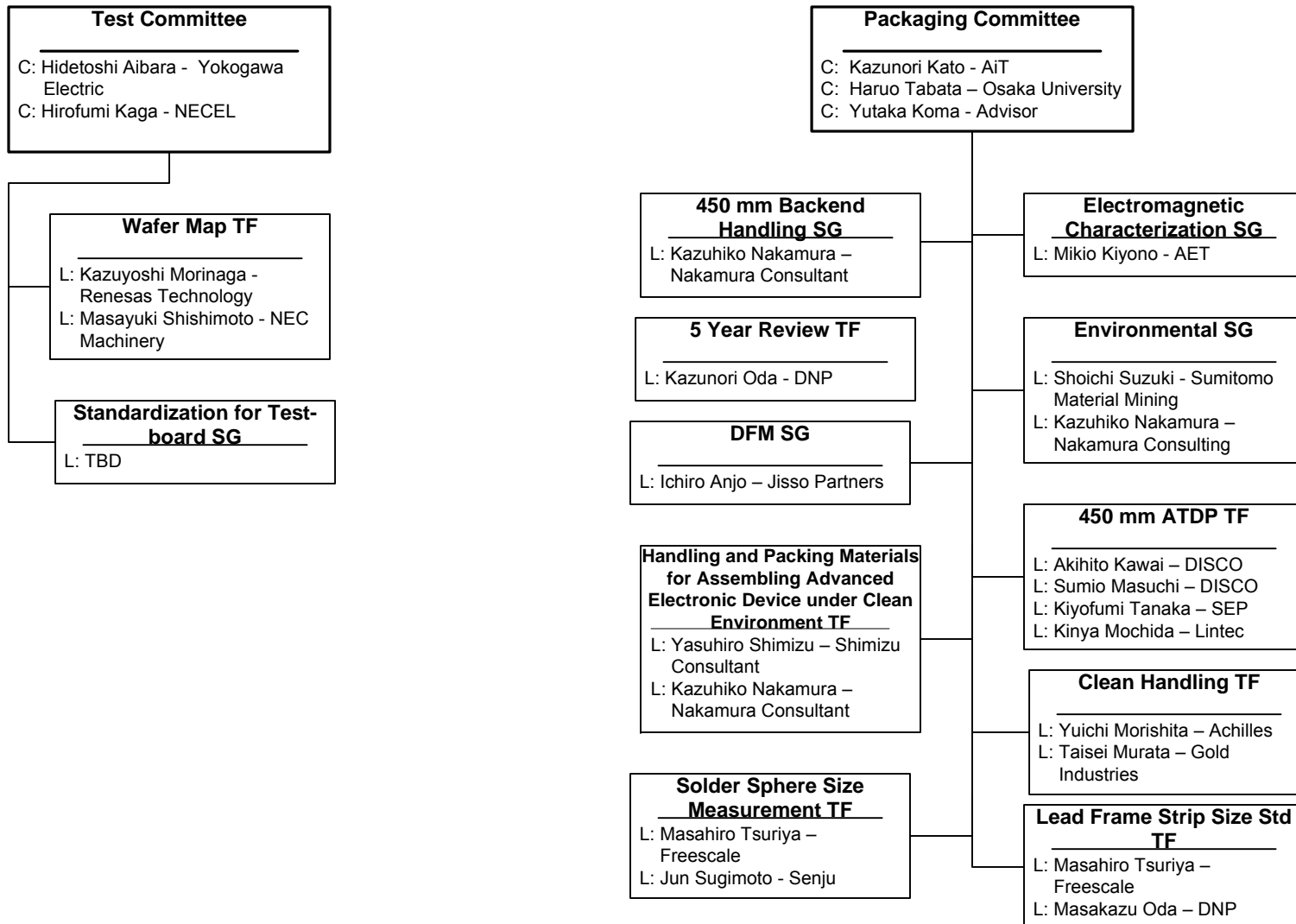
SEMI Japan Silicon Wafer Committee



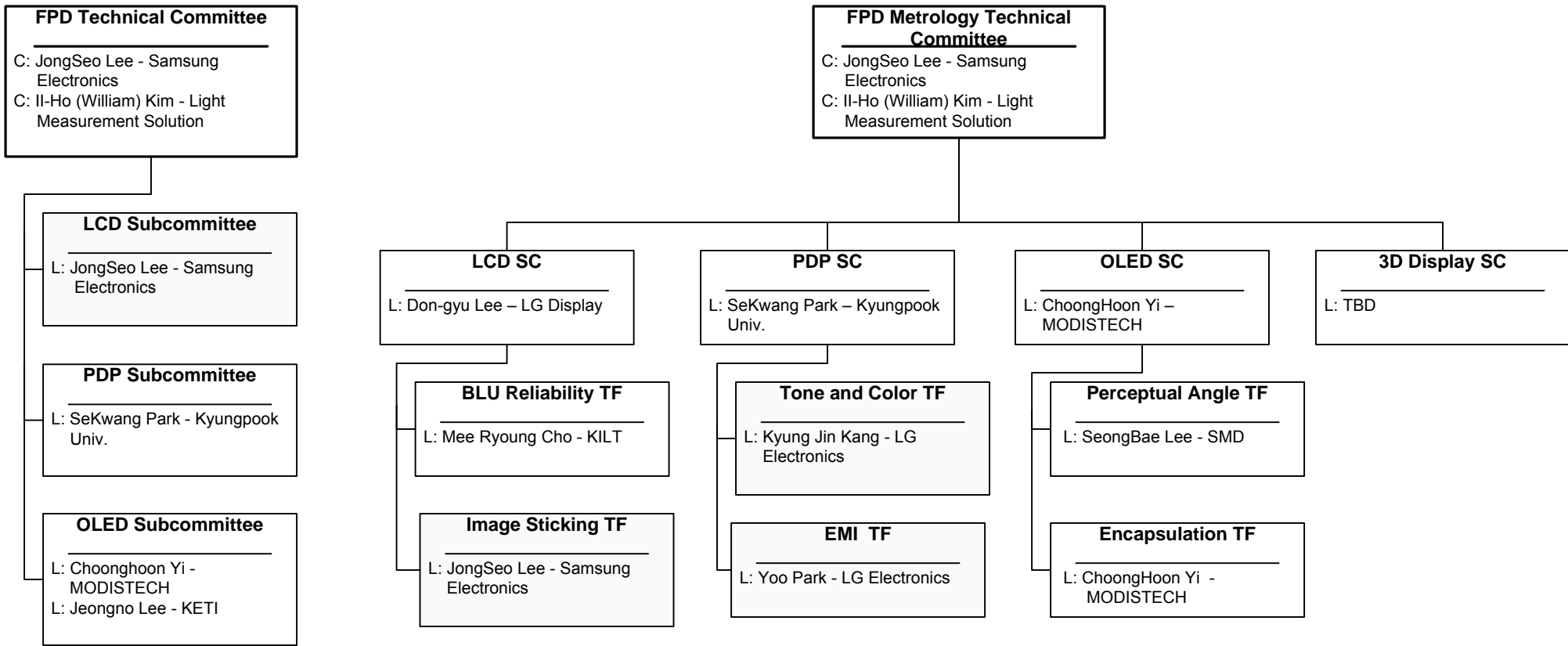
SEMI Japan Compound and Micropatterning Committees



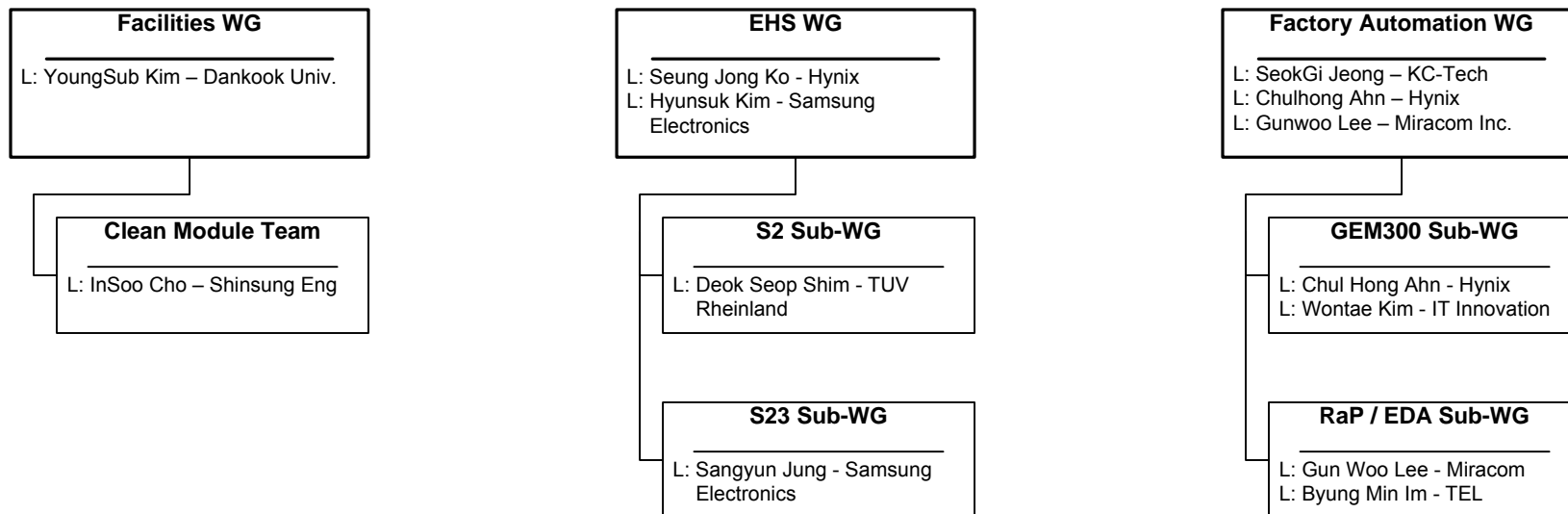
SEMI Japan Test and Packaging Committees



SEMI Korea Flat Panel Display Standards Organization



SEMI Korea Semiconductor Standards Organization



SEMI N.A. Regional Standards Organization

Co-Chairs: Jackie Ferrell – ISMI, Sean Larsen – AMEC

Compound Semiconductor Materials Committee

C: Russ Kremer - Freiberger
Compound Materials
C: James Oliver - Northrop Grumman

Environmental Health & Safety Committee

C: Chris Evanston - Salus
Engineering
C: Sean Larsen - AMEC
C: Eric Sklar - Safety Guru
C: James Beasley - ISMI

Facilities Committee

C: Phil Naughton - Applied Materials

Flat Panel Display Committee

C: Bill Colbran – Engenuity Systems

Gases Committee

C: Tim Volin - Parker Hannifin

Information & Control Committee

C: Jack Ghiselli - Consultant
C: David Bricker - Semitool
C: Lance Rist - ISMI

Liquid Chemicals Committee

C: Frank Flowers - FMC
C: Frank Parker - ICL

MEMS Committee

C: Win Baylies - BayTech Group
C: Dan Chilcott - Delphi
C: Mark Crockett - Applied Materials

Metrics Committee

C: David Bouldin - Fab Consulting
C: Tom Pomorski – Productivity
Management Associates

Microlithography Committee

C: Wes Erck – Wes Erck &
Associates
C: Rick Silver - NIST

Physical Interfaces & Carriers Committee

C: Matt Fuller - Entegris
C: Mutaz Haddadin - Intel

Silicon Wafer Committee

C: Dinesh Gupta - STA
C: Noel Poduje - SMS
VC: Win Baylies - BayTech Group

Traceability Committee

C: Win Baylies - BayTech Group
C: Yaw Obeng - NIST

Photovoltaic Committee

C: Heiko Moritz – Caerus Systems
C: Win Baylies – Baytech Group

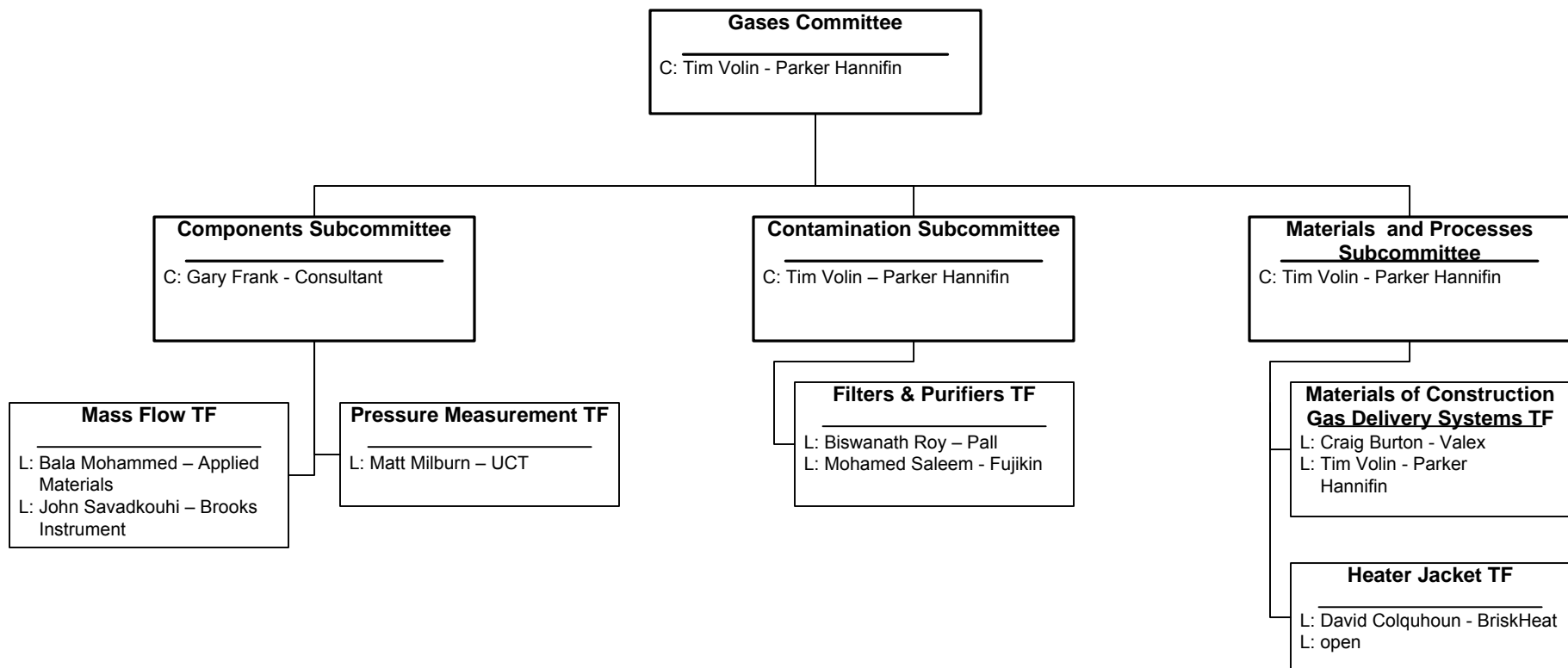
Automated Test Equipment Committee

C: Paul Roddy - Advantest

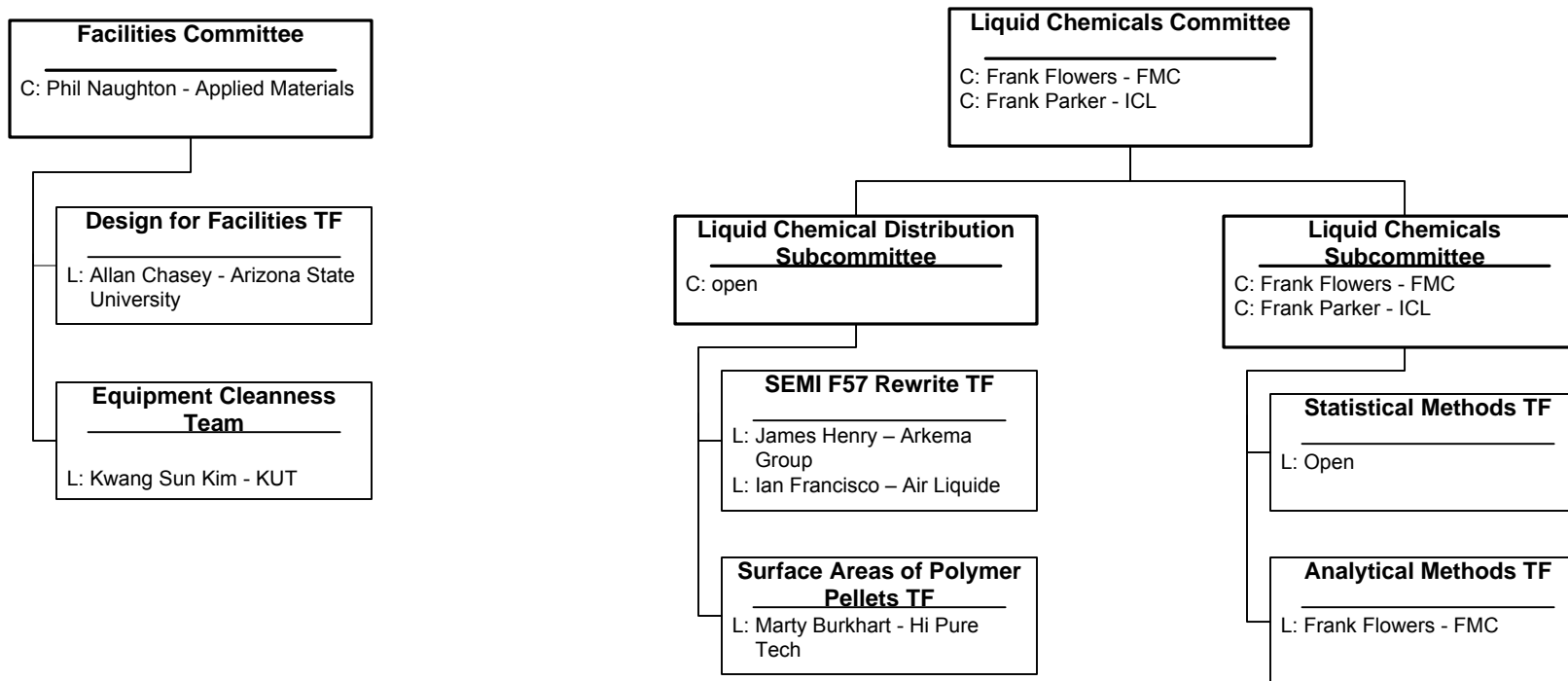
NA RSC Technical Architect Board

C: James Moyne – Applied Materials
C: open

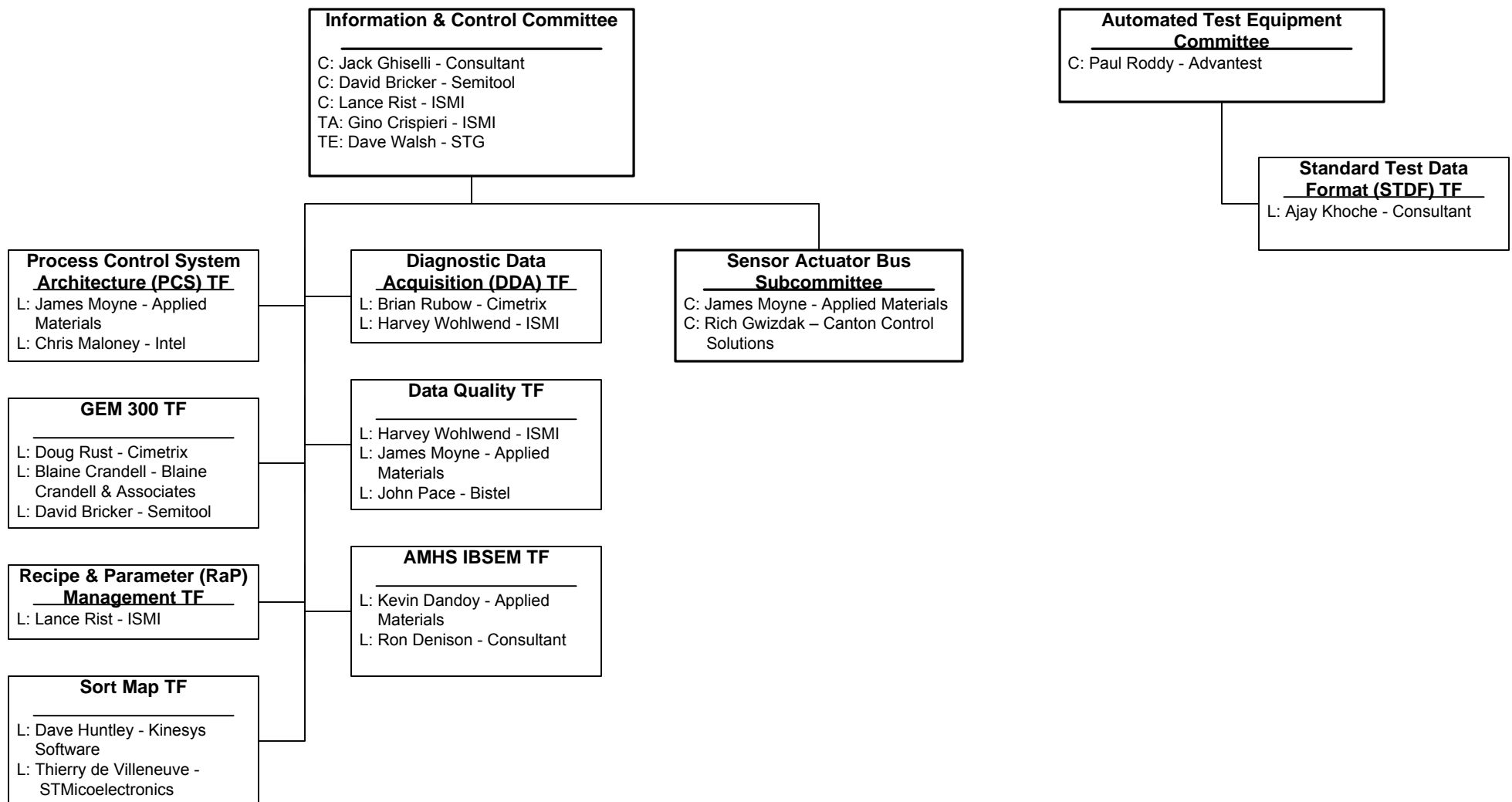
SEMI N.A. Gases Committee



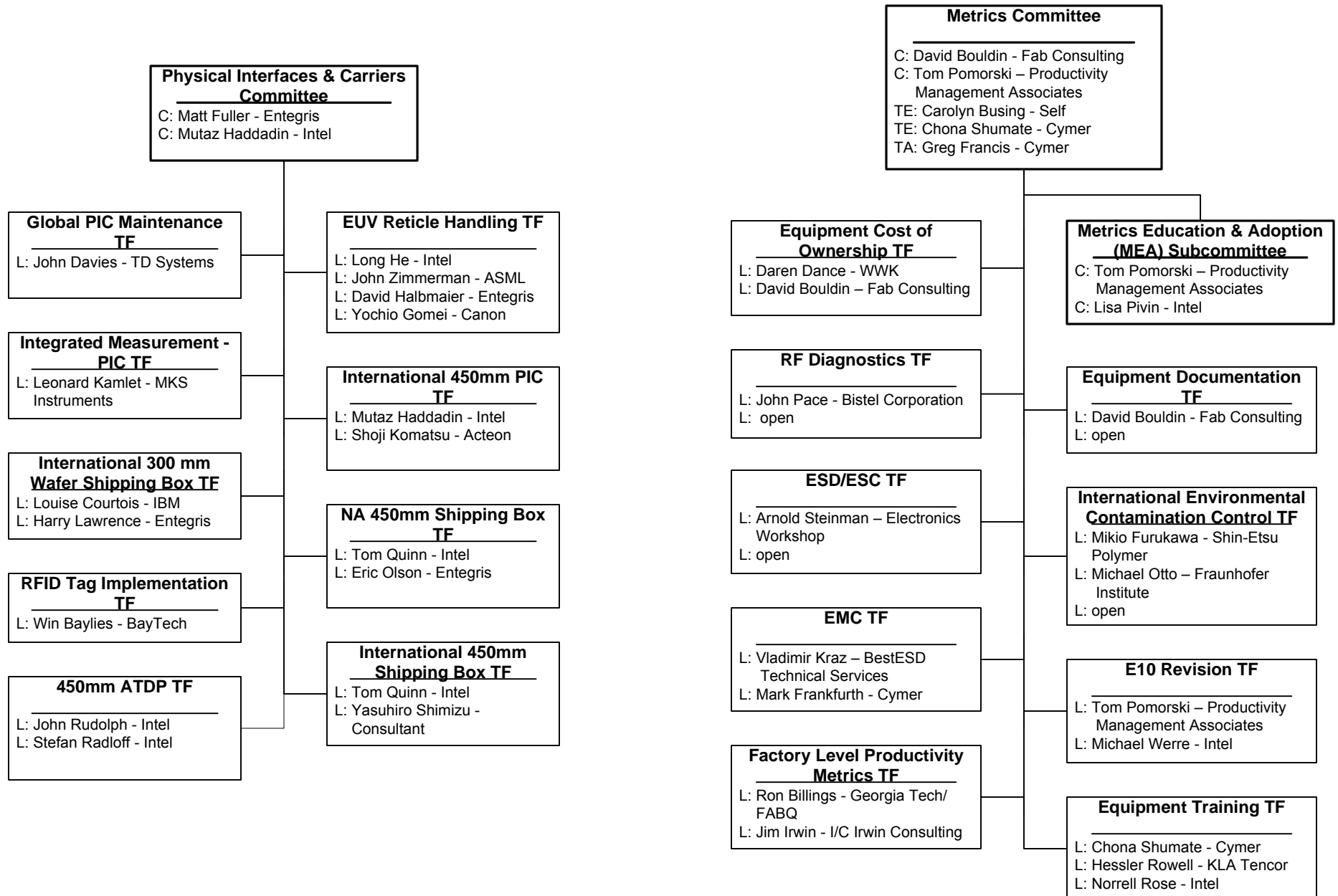
SEMI N.A. Facilities & Liquid Chemicals Committees



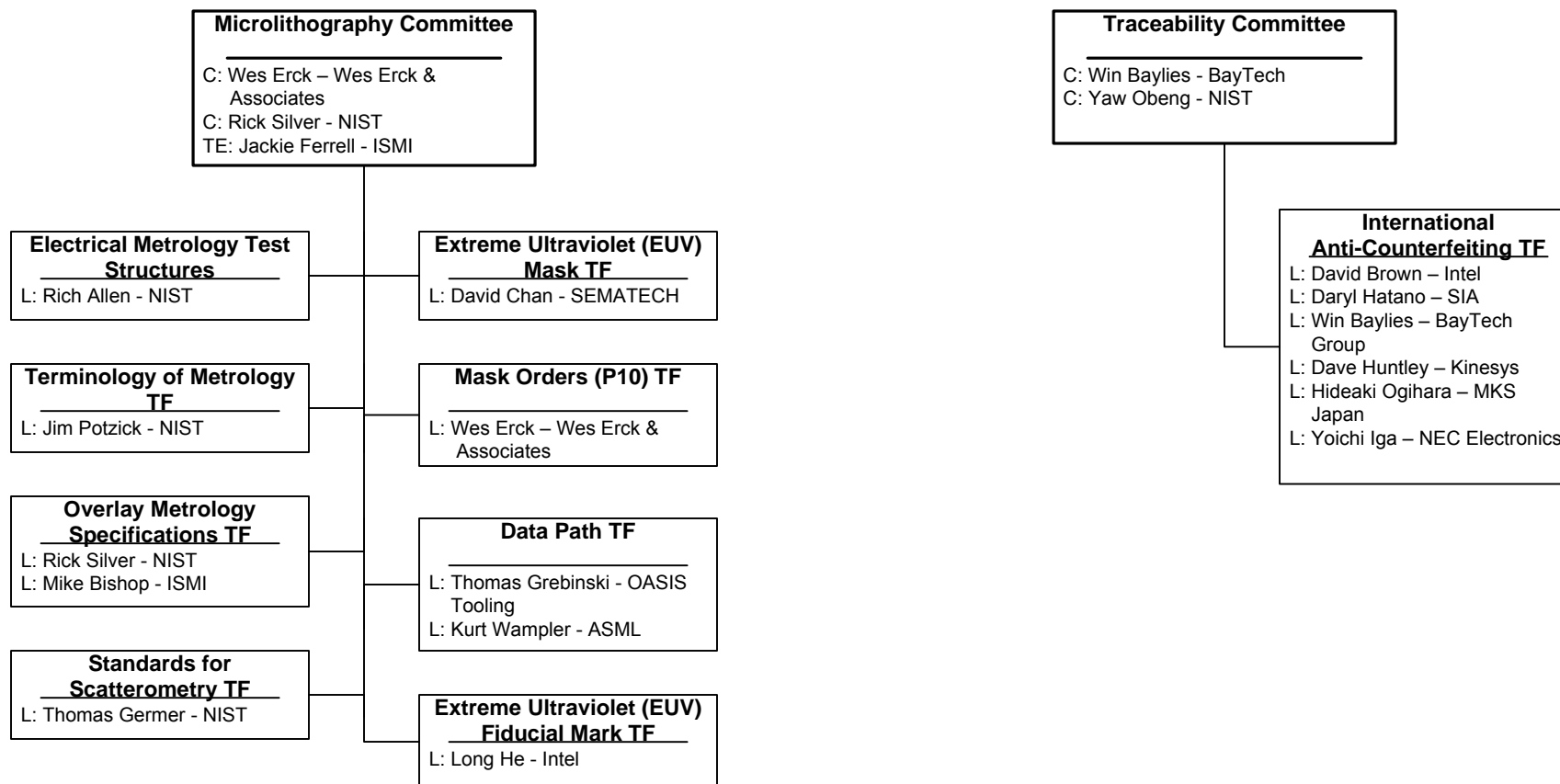
SEMI N.A. Information & Control and Automated Test Equipment Committees



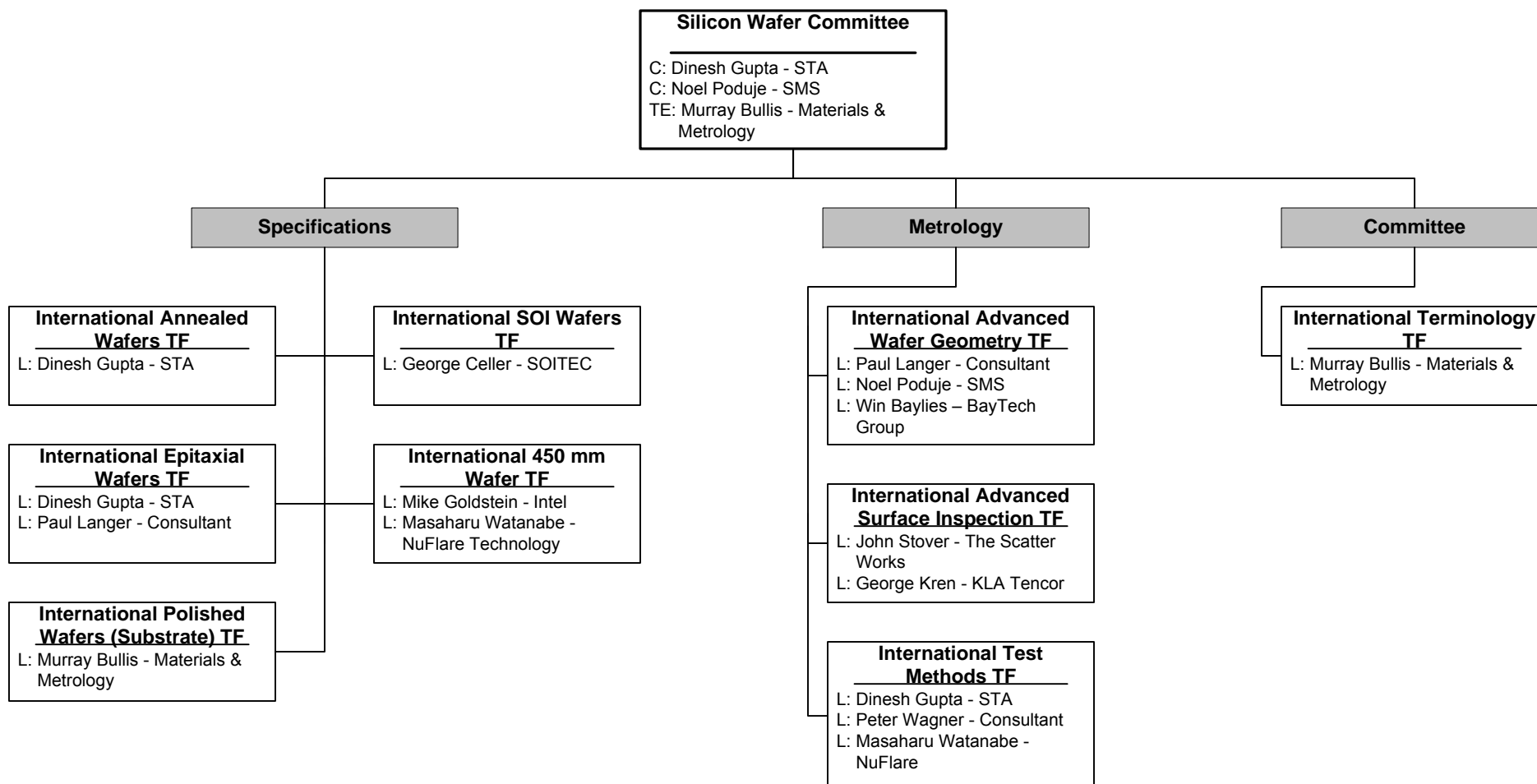
SEMI N.A. Physical Interfaces & Carriers and Metrics Committees



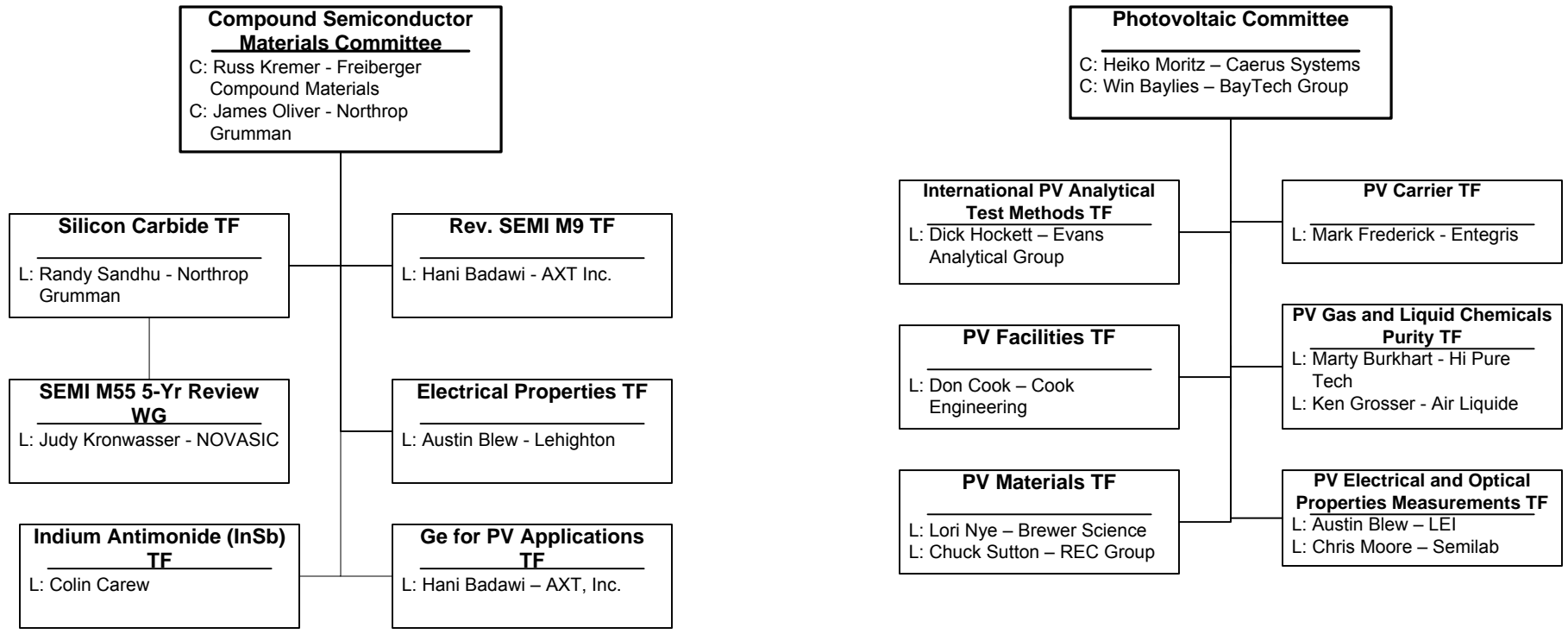
SEMI N.A. Microlithography & Traceability Committees



SEMI N.A. Silicon Wafer Committee



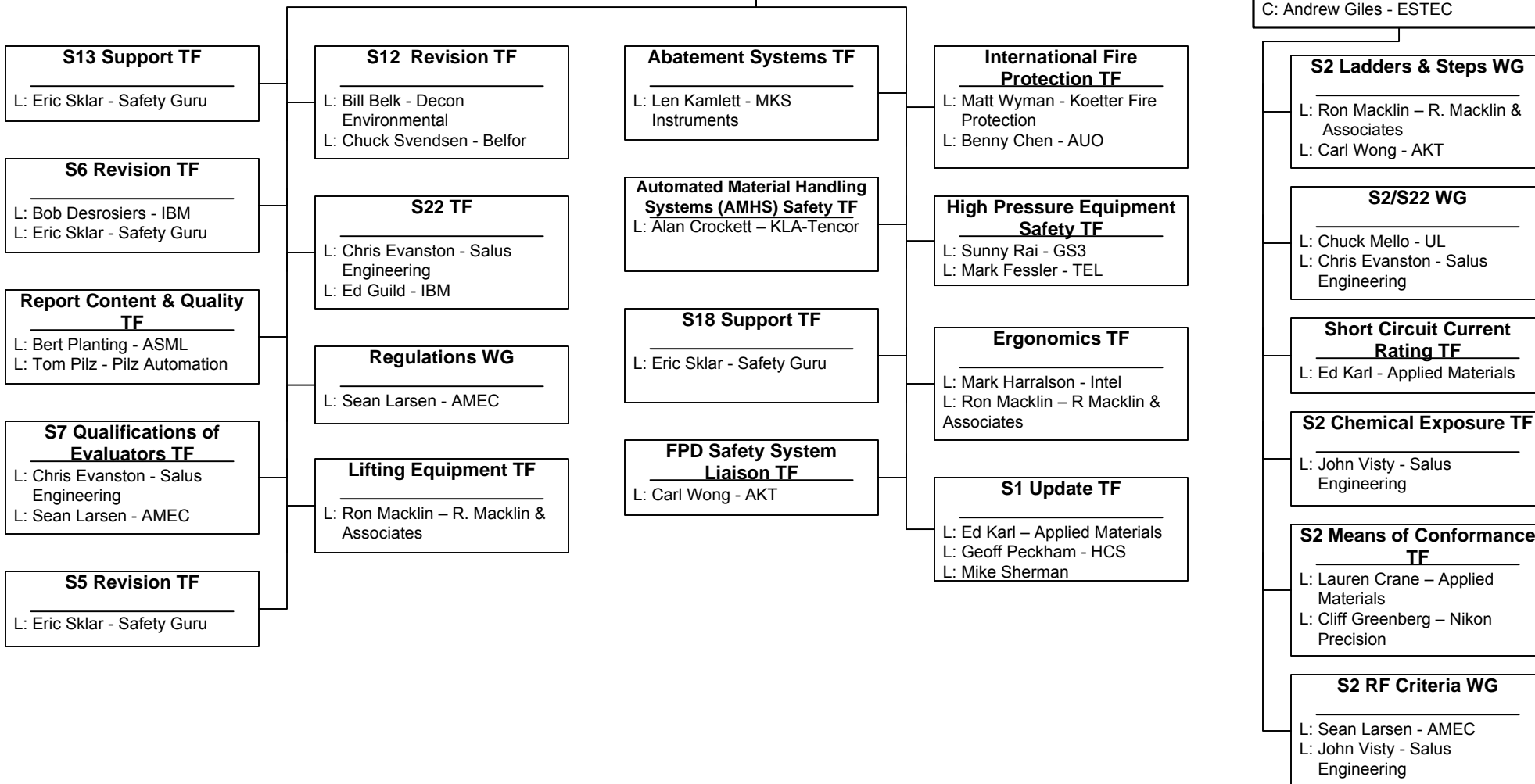
SEMI N.A. Compound Semiconductor & Photovoltaic Committees



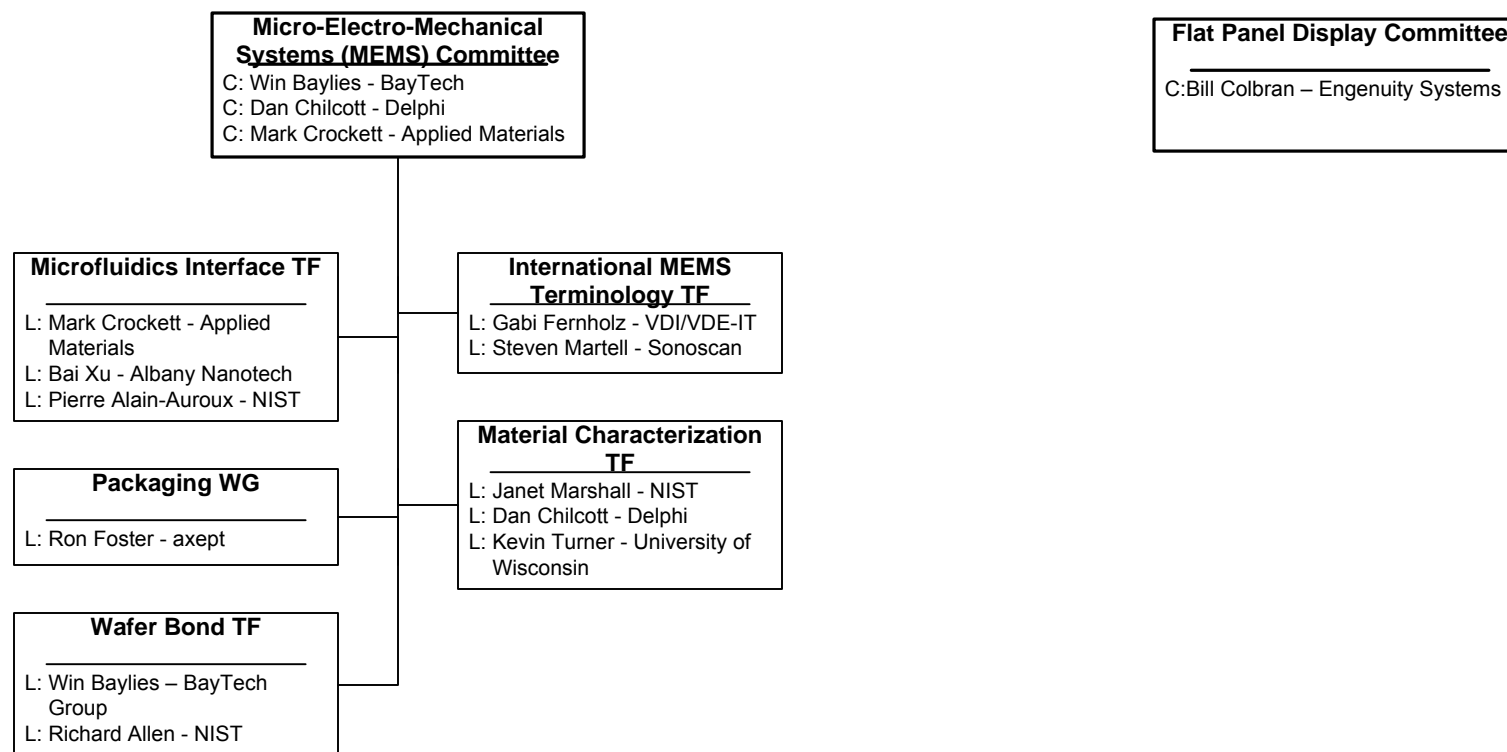
SEMI N.A. Environmental, Health & Safety Committee

Environmental Health & Safety Committee
 C: Chris Evanston – Salus Engineering
 C: Sean Larsen - AMEC
 C: Eric Sklar - Safety Guru
 C: James Beasley - ISMI

Manufacturing Equipment Safety Subcommittee
 C: Mark Harralson - Intel
 C: Cliff Greenberg - Nikon Precision
 C: Andrew Giles - ESTEC



SEMI N.A. MEMS & Flat Panel Display Committees



SEMI Taiwan Standards Organization

ISC Taiwan Advisor

Tzeng-Yow Lin - CMS/ITRI

NARSC Mentor

Bevan Wu – BW & Associates

Information & Control Committee

C: Allan Chen - TSMC

Environmental Health & Safety Committee

C: S. W. Yu - SAHTECH
C: F. M. Hsu - TSMC

Flat Panel Display Committee

C: Tzeng-Yow Lin - CMS/ITRI
C: Jia-Ming Liu - TDMDA

Photovoltaic Committee

C : Jeff Lee - Chroma
C : B. N. Chung - CMS/ITRI
C : YY. Tsai - Delsolar
C : J.S. Chen - PVTC/ITRI
C : Ray Sung - UL Taiwan

SEMI Taiwan Information & Control / Photovoltaic Committees

**Information & Control
Committee Advisor**
Thomas W.Y. Chen - TSMC

**Information & Control
Committee**
C: Allan Chen - TSMC

Liaison - TSIA
Celia Shih - TISA

Factory Integration TF
L : MT Yeh - PSC
L : Robert Weng - TEL
L : H. S You - Energywell

EES TF
L : Allan Chen - TSMC
L : Jack Huang - MKS

**Automated Material
Handling System TF**
L : William Liu - UMC
L : Hu Szn Fan - UMC

Photovoltaic Committee
C : Jeff Lee - Chroma
C : B. N. Chuang - CMS/ITRI
C : YY. Tsai - Delsolar
C : J.S. Chen - PVTC/ITRI
C : Ray Sung - UL Taiwan

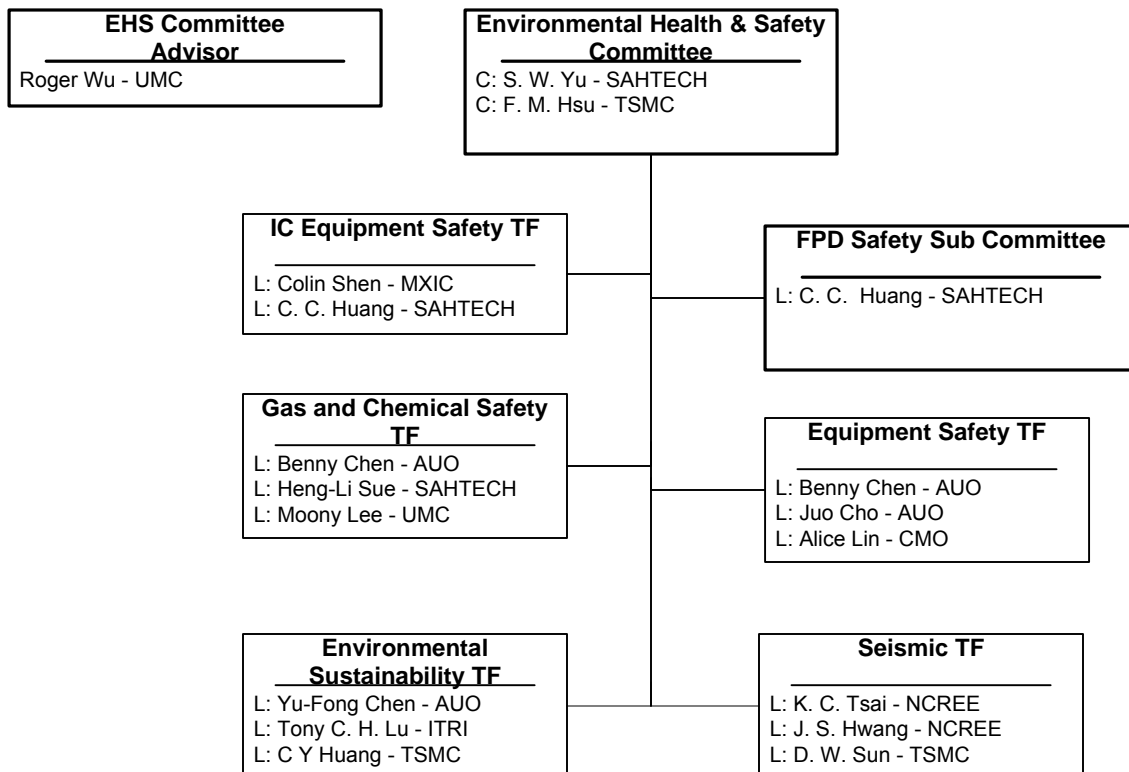
c-Si Cell Appearance TF
L : Jeff Lee - Chroma
L : Jesse Cheng - Kinmac

Vibration Test Method TF
L : Ariel Chiu - AUO
L : C.C. Lin - a2peak
L : T.C. Wu - CMS-ITRI
L : K.T. Lee - King Design

**Equipment Interface Stds
Coordination WG**
L : TBD

**Cell Specification
Coordination WG**
L : Jack Huang - Delsolar

SEMI Taiwan Environmental, Health & Safety Committee



SEMI Taiwan Flat Panel Display Committee

